

RMF500 Technical Specifications

PRINTER	RMF500	
CONSTRUCTION	Build Volume (W × D × H)	
	Single Extruder Print	Dual Extruder Print
	500 × 500 × 500 mm	500 × 500 × 500 mm
	Machine Size (W × D × H)	
		1340 × 990 × 2370 mm
ELECTRICAL	Power Supply Input	3-Phase 380V AC 25 A
GENERAL	Print Technology Print Head Filament Diameter XYZ Positioning Resolution Print Head Travel Speed Build Plate Max Build Plate Temperature Heated Bed Material Build Plate Leveling Supported Materials Layer Height Nozzle Diameter Max Nozzle Temperature Connectivity Operating Ambient Temperature Storage Temperature	FFF Independent Dual Electric Nozzle Extrusion System 1.75 mm 1, 1, 0.09765 micron ≤ 300 mm/s PEI Build Plate with Vacuum Manifold 110°C Steel Auto leveling Raise3D Industrial PA12 CF, Raise3D Industrial PA12 CF Support (PPA CF, PPS CF, PET CF and PPA GF Coming soon) 0.05-0.75 mm 0.6 mm (Default), 0.8 mm (Coming soon) 330°C Wi-Fi, LAN, USB port, Live camera 15-30°C, 30-70% RH Non-Condensing (HOLD) -40°C to +54°C, 10-85% RH Non-Condensing (HOLD)
SOFTWARE	Slicing Software Supported File Types Supported OS Machine Code Type	ideaMaker STL/ OBJ/ 3MF/ OLTP Windows/ macOS/ Linux GCODE
PRINTER CONTROLLER	User Interface Network Screen Resolution Motion Controller Logic Controller Memory Onboard Flash Micro SD Card OS Ports	13.3-inch Touchscreen Ethernet, Wireless 802.11 b/g/n, Dual Mode Wi-Fi 1920 × 1080 Rockchip ARM Cortex-M4 Rockchip RK3399 ARM Dual Cortex-A72 and Quad Cortex-A53 1.8 GHz 2 GB 16 GB 128 GB Embedded Linux USB 2.0 × 1